

LOCTITE ABLESTIK CE 3103

December 2016

PRODUCT DESCRIPTION

LOCTITE ABLESTIK CE 3103 provides the following product characteristics:

Technology	Epoxy
Appearance	Silver
Filler Type	Silver
Filler Weight, %	75
Product Benefits	• One component • Electrically conductive • Pb-free alternative to solder • Low CTE • Low cure temperature • Exceptional thermo-mechanical junction reliability
Cure	Heat cure
Operating Temperature	150 °C
Application	Electrically Conductive Adhesive
Typical Package Application	SMD component attach
Substrates	Sn, Sn/Pb and OSP-Cu printed circuit boards

LOCTITE ABLESTIK CE 3103 adhesive is a lead-free alternative to solder. It is highly compatible with existing SMT assembly processes and can be applied by syringe dispense or printing.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Viscosity @ 25 °C, mPa·s (cP)	50,000
Specific Gravity	3.5
Work Life @ 24°C, hours	24
Shelf Life @ -40°C, days	183
Flash Point - See SDS	

TYPICAL CURING PERFORMANCE Cure Schedule

Reflow:

3 minutes @ 150°C or

5 minutes @ 125°C

Convection:

8 minutes @ 125°C or

5 minutes @ 150°C

NOTE: LOCTITE ABLESTIK CE 3103 cures completely during a typical reflow cycle and does not require postcure operation.

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

TYPICAL PROPERTIES OF CURED MATERIAL

Physical Properties :

Coefficient of Thermal Expansion ppm/°C:

Below Tg	45
Above Tg	146

Glass Transition Temperature (Tg), °C 109

Tensile Modulus, DMTA :

@ 25 °C	N/mm ²	5,600
	(psi)	(812,000)
@ 150 °C	N/mm ²	200
	(psi)	(29,000)

Extractable Ionic Content, ppm:

Chloride (Cl ⁻)	<50
Sodium (Na ⁺)	<10
Potassium (K ⁺)	<5

Electrical Properties:

Volume Resistivity @ 25°C, ohm-cm	0.0007
-----------------------------------	--------

TYPICAL PERFORMANCE OF CURED MATERIAL

Tensile Lap Shear Strength, MPa	8
---------------------------------	---

PERFORMANCE AND RELIABILITY DATA

Contact resistance stability has been evaluated using a 6 mil (150µm) print on a daisy chain pattern without resistors (with 10 resistor positions).

Initial Contact Resistance:

Chain Average:

OSP coated Cu, ohm	0.139
SnPb, ohm	0.3283
Sn, ohm	0.5152

Individual Pad:

OSP coated Cu, ohm	0.0069
SnPb, ohm	0.0164
Sn, ohm	0.0258

% Change from Initial Reading:

500 hours, 85°C / 85% RH:

OSP coated Cu, %	8
SnPb, %	4
Sn, %	-53

1,000 hours, 85°C / 85% RH:

OSP coated Cu, %	9
SnPb, %	47
Sn, %	-68

GENERAL INFORMATION

For safe handling information on this product, consult the Safety Data Sheet, (SDS).

THAWING:

1. Allow container to reach room temperature before use.

Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

STORAGE:

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: -40 to -35°C. Storage below -40°C can adversely affect product properties (freeze-thaw voids).

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

$(^{\circ}\text{C} \times 1.8) + 32 = ^{\circ}\text{F}$
 $\text{kV/mm} \times 25.4 = \text{V/mil}$
 $\text{mm} / 25.4 = \text{inches}$
 $\text{N} \times 0.225 = \text{lb}$
 $\text{N/mm} \times 5.71 = \text{lb/in}$
 $\text{psi} \times 145 = \text{N/mm}^2$
 $\text{MPa} = \text{N/mm}^2$
 $\text{N}\cdot\text{m} \times 8.851 = \text{lb}\cdot\text{in}$
 $\text{N}\cdot\text{m} \times 0.738 = \text{lb}\cdot\text{ft}$
 $\text{N}\cdot\text{mm} \times 0.142 = \text{oz}\cdot\text{in}$
 $\text{mPa}\cdot\text{s} = \text{cP}$

Disclaimer

Note:

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

Any liability in respect of the information in the Technical Data Sheet or any other written or oral recommendation(s) regarding the concerned product is excluded, except if otherwise explicitly agreed and except in relation to death or personal injury caused by our negligence and any liability under any applicable mandatory product liability law.

In case products are delivered by Henkel Belgium NV, Henkel Electronic Materials NV, Henkel Nederland BV, Henkel Technologies France SAS and Henkel France SA please additionally note the following:

In case Henkel would be nevertheless held liable, on whatever legal ground, Henkel's liability will in no event exceed the amount of the concerned delivery.

In case products are delivered by Henkel Colombiana, S.A.S. the following disclaimer is applicable:

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

Any liability in respect of the information in the Technical Data Sheet or any other written or oral recommendation(s) regarding the concerned product is excluded, except if otherwise explicitly agreed and except in relation to death or personal injury caused by our negligence and any liability under any applicable mandatory product liability law.

In case products are delivered by Henkel Corporation, Resin Technology Group, Inc., or Henkel Canada Corporation, the following disclaimer is applicable:

The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, **Henkel Corporation specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Henkel Corporation's products. Henkel Corporation specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits.** The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Henkel Corporation patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent applications.

Trademark usage: [Except as otherwise noted] All trademarks in this document are trademarks and/or registered trademarks of Henkel and its affiliates in the U.S. and elsewhere.

Reference 1